

TSMC-00-166



December 14, 2000

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/679,514 10/06/00

Hung-Jen Hsu, Yu-Kung Hsiao,
Chih-Kung Chang, Sheng-Liang Pan,
Kuo-Liang Lu

A METHOD TO IMPROVE PASSIVATION
OPENINGS BY REFLOW OF PHOTORESIST
TO ELIMINATE TAPE RESIDUE

Grp. Art Unit:

RECEIVED
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MAIL ROOM

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 5,063,655 to Lamey et al., "Method to
Integrate Drive/Control Devices and Ink Jet on Demand Devices
in a Single Printhead Chip", teaches a method to integrate the
driver pulse circuitry and the resistors of an ink jet printer
onto the printer head.

U.S. Patent 5,731,243 to Peng et al., "Method of Cleaning Residue on a Semiconductor Wafer Bonding Pad", teaches a method to reduce protective tape adhesive contamination.

U.S. Patent 6,060,378 to Rolfson, "Semiconductor Bonding Pad for Better Reliability", discloses a method to form bonding pads with improved reliability.

U.S. Patent 6,025,275 to Efland et al., "Method of Forming Improved Thick Plated Copper Interconnect and Associated Auxiliary Metal Interconnect", discloses a method to form thick plated copper interconnects.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a horizontal line extending to the right.

Stephen B. Ackerman,
Reg. No. 37761